



NCE N-Channel Enhancement Mode Power MOSFET

Description

The NCE3035Q uses advanced trench technology and design to provide excellent $R_{DS(ON)}$ with low gate charge. It can be used in a wide variety of applications.

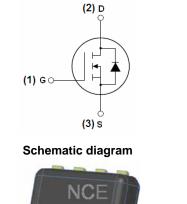
General Features

- V_{DS} =30V,I_D =35A
 R_{DS(ON)} < 5.5mΩ @ V_{GS}=10V
 R_{DS(ON)} < 9.5mΩ @ V_{GS}=4.5V
- High density cell design for ultra low Rdson
- Fully characterized avalanche voltage and current
- Good stability and uniformity with high E_{AS}
- Excellent package for good heat dissipation
- Special process technology for high ESD capability

Application

- Secondary side synchronous rectifier
- High side switch in POL DC/DC converter

100% UIS TESTED!





Marking and pin assignment

s[1 ●	8]D
s[2	7]D
s 3	6 D
G[4	5]D
DFN 3x3 EI	P top view

Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
NCE3035Q	NCE3035Q	DFN 3x3 EP	-	-	-

Absolute Maximum Ratings (Tc=25°Cunless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	Vds	30	V
Gate-Source Voltage	Vgs	±20	V
Drain Current-Continuous	Ι _D	35	А
Pulsed Drain Current	I _{DM}	120	A
Maximum Power Dissipation	PD	35	W
Derating factor		0.28	W/℃
Single pulse avalanche energy (Note 5)	E _{AS}	150	mJ
Operating Junction and Storage Temperature Range	T _J ,T _{STG}	-55 To 150	°C





Thermal Characteristic

Thermal Resistance, Junction-to-Case ^(Note 2)	R _{θJC}	3.6	°C/W
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Electrical Characteristics (TC=25°C unless otherwise noted)

Parameter	Symbol	Condition	Min	Тур	Max	Unit
Off Characteristics	·		•			
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V I _D =250µA	30	33	-	V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =30V,V _{GS} =0V	-	-	1	μA
Gate-Body Leakage Current	I _{GSS}	V_{GS} =±20V, V_{DS} =0V	-	-	±100	nA
On Characteristics (Note 3)	·		•			
Gate Threshold Voltage	V _{GS(th)}	V _{DS} =V _{GS} ,I _D =250µA	1	1.6	3	V
Drain-Source On-State Resistance	Beauty	V _{GS} =10V, I _D =12A	-	4.8	5.5	- mΩ
	R _{DS(ON)}	V _{GS} =4.5V, I _D =10A	-	8.2	9.5	
Forward Transconductance	g fs	V _{DS} =10V,I _D =12A	30	-	-	S
Dynamic Characteristics (Note4)			•			
Input Capacitance	C _{lss}	V _{DS} =15V,V _{GS} =0V,	-	1265	-	PF
Output Capacitance	C _{oss}		-	600	-	PF
Reverse Transfer Capacitance	C _{rss}	F=1.0MHz	-	130	-	PF
Switching Characteristics (Note 4)	·		•			
Turn-on Delay Time	t _{d(on)}	V _{DD} =15V,I _D =12A V _{GS} =10V,R _{GEN} =6Ω	-	18	-	nS
Turn-on Rise Time	tr		-	10	-	nS
Turn-Off Delay Time	t _{d(off)}		-	34	-	nS
Turn-Off Fall Time	t _f		-	10	-	nS
Total Gate Charge	Qg)/ _15)// _120	-	19	-	nC
Gate-Source Charge	Q _{gs}	V_{DS} =15V,I _D =12A,	-	2.7	-	nC
Gate-Drain Charge	Q _{gd}	V _{GS} =10V	-	2.5	-	nC
Drain-Source Diode Characteristics						
Diode Forward Voltage (Note 3)	V _{SD}	V _{GS} =0V,I _S =12A	-	0.85	1.2	V
Diode Forward Current (Note 2)	Is		-	-	25	Α
Reverse Recovery Time	t _{rr}	TJ = 25°C, IF = 12A	-	-	47	nS
Reverse Recovery Charge	Qrr	di/dt = 100A/µs(Note3)	-	-	25	nC
Forward Turn-On Time	t _{on}	Intrinsic turn-on time is negligible (turn-on is dominated by LS+LD)				

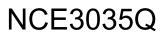
Notes:

- 1. Repetitive Rating: Pulse width limited by maximum junction temperature.
- **2.** Surface Mounted on FR4 Board, $t \le 10$ sec.
- **3.** Pulse Test: Pulse Width \leq 300µs, Duty Cycle \leq 2%.
- 4. Guaranteed by design, not subject to production
- **5.** EAS condition: Tj=25 $^\circ C$,V_DD=15V,V_G=10V,L=0.1mH,Rg=25\Omega



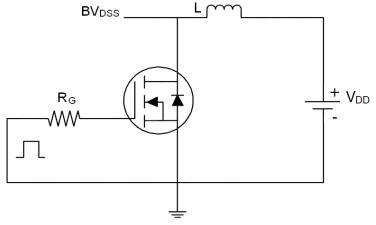
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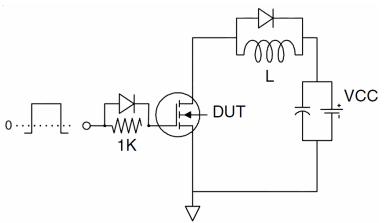


Test Circuit

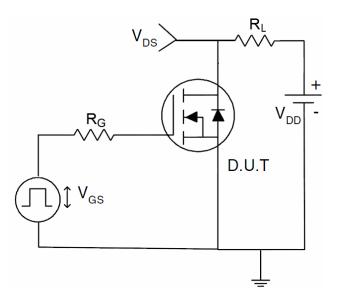
1) E_{AS} Test Circuits



2) Gate Charge Test Circuit



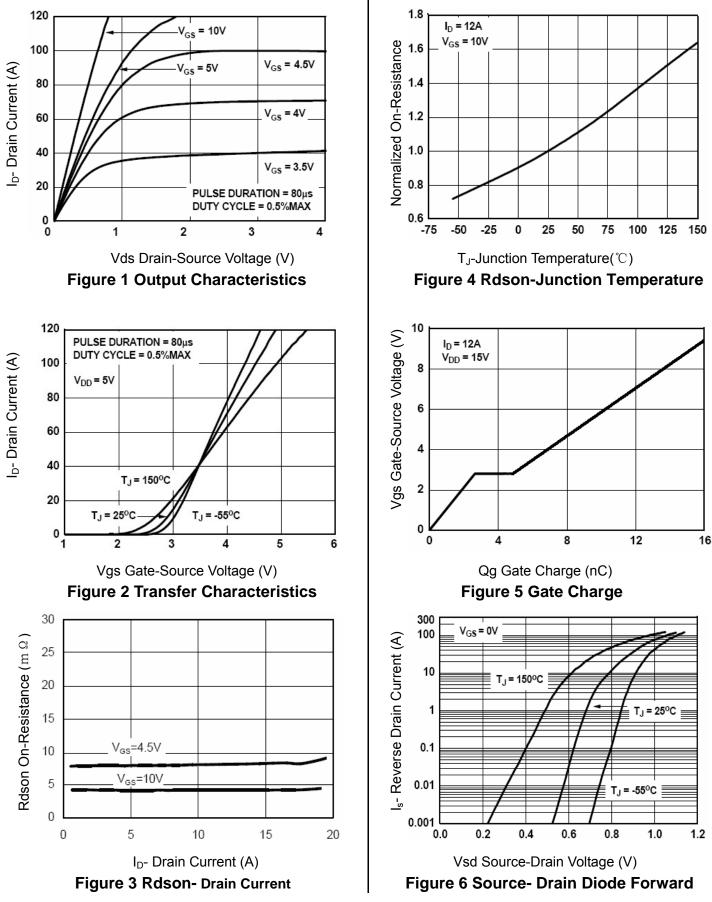
3) Switch Time Test Circuit







Typical Electrical and Thermal Characteristics (Curves)





1

0.1

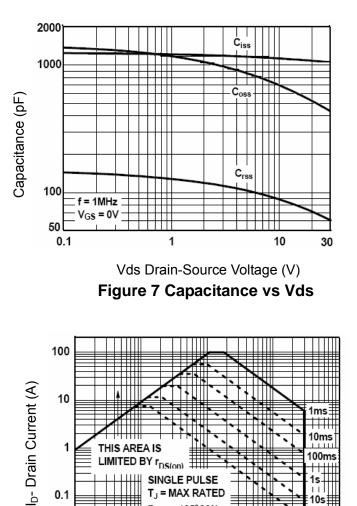
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0.01

THIS AREA IS LIMITED BY r_{DS(on)}

0.1

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Vds Drain-Source Voltage (V) **Figure 8 Safe Operation Area**

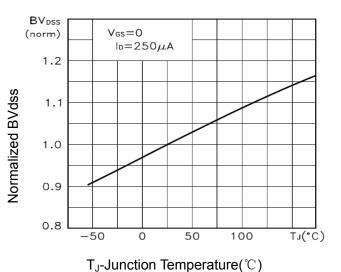
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SINGLE PULSE

TJ = MAX RATED

 $R_{\theta JA} = 125^{\circ}C/W$

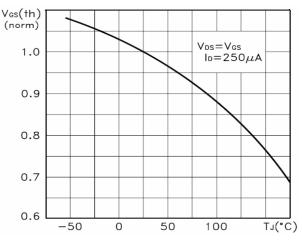
T_A = 25°C



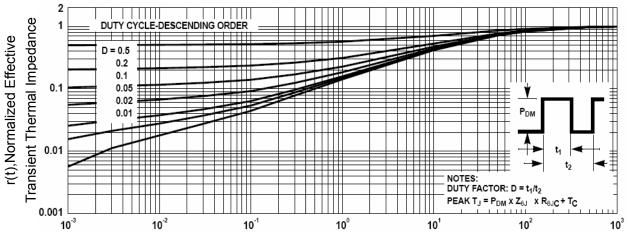
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NCE3035Q

Figure 9 BV_{DSS} vs Junction Temperature



T_J-Junction Temperature ($^{\circ}C$) Figure 10 V_{GS(th)} vs Junction Temperature



10ms

100ms

1s

1

10s

DC

100

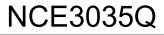
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Square Wave Pluse Duration(sec) Figure 11 Normalized Maximum Transient Thermal Impedance

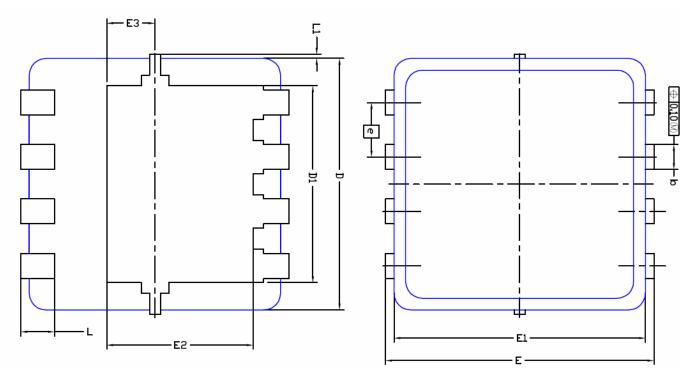


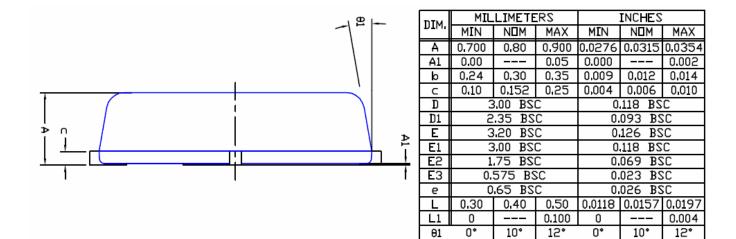
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DFN3X3 EP Package Information

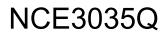






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